

C3  
12. (Amended) The method as recited in claim 9, further comprising:  
plugging a stub that supports the printed circuit board of the installed IC package into a  
substrate of the tray.

D1  
C4  
13. (Twice Amended) A method for decapsulating installed integrated circuit (IC)  
packages, comprising:  
receiving an IC package permanently installed onto a first surface of a printed circuit board  
(PCB) wherein the printed circuit board includes a second surface located below the first surface of  
the printed circuit board;  
spraying a decapsulation fluid onto the installed IC package via an injection head clamped to  
the installed IC package, the injection head having a nozzle disposed above the installed IC package  
that is in fluid communication with an inlet port of said injection head, and a return port that is in  
fluid communication with an outlet port of the injection head.

14. (Amended) The method as recited in claim 13, further comprising:  
controlling a flow of the decapsulation fluid through a pair of tubes that couple an extender  
to the injection head using a corresponding pair of valves.

C5  
15. (Amended) The method as recited in claim 13, further comprising:  
plugging a stub that supports the PCB of the installed IC package into a substrate.

16. (Amended) The method as recited in Claim 13 further comprising:  
forming a seal between injection head and the installed IC package to prevent decapsulation  
fluid from contacting the PCB of the installed IC package.